

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:

CORRECTIVE ASSIGNMENT

NATURE OF CONVEYANCE:

Corrective Assignment to correct the Title previously recorded on Reel 018559 Frame 0627. Assignor(s) hereby confirms the Assignment of Assignors Interest.

CONVEYING PARTY DATA

Name	Execution Date
Hiromitsu Takeda	03/09/2006
Shigeyoshi Hirashima	03/09/2006
Toshiki Kagami	03/09/2006
Atsushi Oda	03/09/2006
Katsuhisa Ono	03/09/2006
Yoshiaki Haba	03/09/2006

RECEIVING PARTY DATA

Name:	Sony Corporation
Street Address:	7-35 Kitashinagawa
City:	Shinagawa-ku, Tokyo 141-0001
State/Country:	JAPAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	10561697

CORRESPONDENCE DATA

Fax Number: (312)876-7934
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Email: bhannon@sonnenschein.com
Correspondent Name: Sonnenschein Nath & Rosenthal LLP
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ATTORNEY DOCKET NUMBER:

09792909-6567

PATENT

REEL: 018729 FRAME: 0117

500204469

OP \$40.00 10561697

NAME OF SUBMITTER:

David R. Metzger

Total Attachments: 7

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11/29/2006
500185281

SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
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Total Attachments: 3

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ASSIGNMENT

Docket Number: _____

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in
PLATEN PLATE AND LIQUID EJECTION APPARATUS

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Application No.: 10/561,697 Filing Date: 12/22/2005

This assignment executed on the dates indicated below.

Hikomitsu TAKEDA

Name of first or sole inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of first or sole inventor

Hikomitsu Takeda

March 9, 2006

Signature of first or sole inventor

Date of this assignment

Shigeyoshi HIRASHIMA

Name of second inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of second inventor

Shigeyoshi Hirashima

March 9, 2006

Signature of second inventor

Date of this assignment

Toshiki KAGAMI

Name of third inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of third inventor

Toshiki Kagami

March 9, 2006

Signature of third inventor

Date of this assignment

Atsushi ODA

Name of fourth inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of fourth inventor

Atsushi Oda

MARCH 9, 2006

Signature of fourth inventor

Date of this assignment

Katsuhisa ONO

Name of fifth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of fifth inventor

Katsuhisa Ono

March 9, 2006

Signature of fifth inventor

Date of this assignment

Yoshiaki HABA

Name of sixth inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of sixth inventor

Signature of sixth inventor

Yoshiaki Haba

March 9, 2006

Date of this assignment

Name of seventh inventor

Execution date of U.S. Patent Application

Residence of seventh inventor

Signature of seventh inventor

Date of this assignment

Name of eighth inventor

Execution date of U.S. Patent Application

Residence of eighth inventor

Signature of eighth inventor

Date of this assignment

Name of ninth inventor

Execution date of U.S. Patent Application

Residence of ninth inventor

Signature of ninth inventor

Date of this assignment